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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2688
Number of Logic Elements/Cells	-
Total RAM Bits	1032192
Number of I/O	456
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2v2000-4fgg676i

Figure 12 provides examples illustrating the use of the SSTL2_I_DCI, SSTL2_II_DCI, SSTL3_I_DCI, and SSTL3_II_DCI I/O standards. For a complete list, see the [Virtex-II Platform FPGA User Guide](#).

	SSTL2_I	SSTL2_II	SSTL3_I	SSTL3_II
Conventional				
DCI Transmit Conventional Receive				
Conventional Transmit DCI Receive				
DCI Transmit DCI Receive				
Bidirectional	N/A		N/A	
Reference Resistor	$VRN = VRP = R = Z_0$	$VRN = VRP = R = Z_0$	$VRN = VRP = R = Z_0$	$VRN = VRP = R = Z_0$
Recommended $Z_0^{(2)}$	50 Ω	50 Ω	50 Ω	50 Ω

Notes:

1. The SSTL-compatible 25Ω series resistor is accounted for in the DCI buffer, and it is not DCI controlled.
2. Z_0 is the recommended PCB trace impedance.

DS031_65b_112502

Figure 12: SSTL DCI Usage Examples

Sum of Products

Each Virtex-II slice has a dedicated OR gate named ORCY, ORing together outputs from the slices carryout and the ORCY from an adjacent slice. The ORCY gate with the dedicated Sum of Products (SOP) chain are designed for implementing

large, flexible SOP chains. One input of each ORCY is connected through the fast SOP chain to the output of the previous ORCY in the same slice row. The second input is connected to the output of the top MUXCY in the same slice, as shown in **Figure 25**.

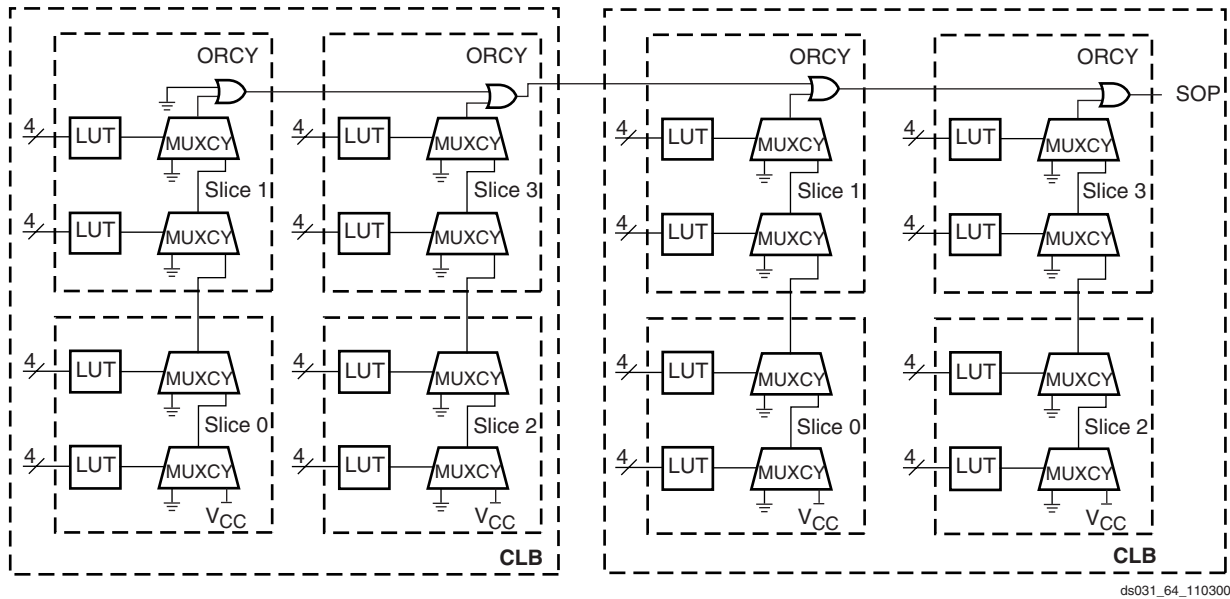


Figure 25: Horizontal Cascade Chain

LUTs and MUXCYs can implement large AND gates or other combinatorial logic functions. **Figure 26** illustrates

LUT and MUXCY resources configured as a 16-input AND gate.

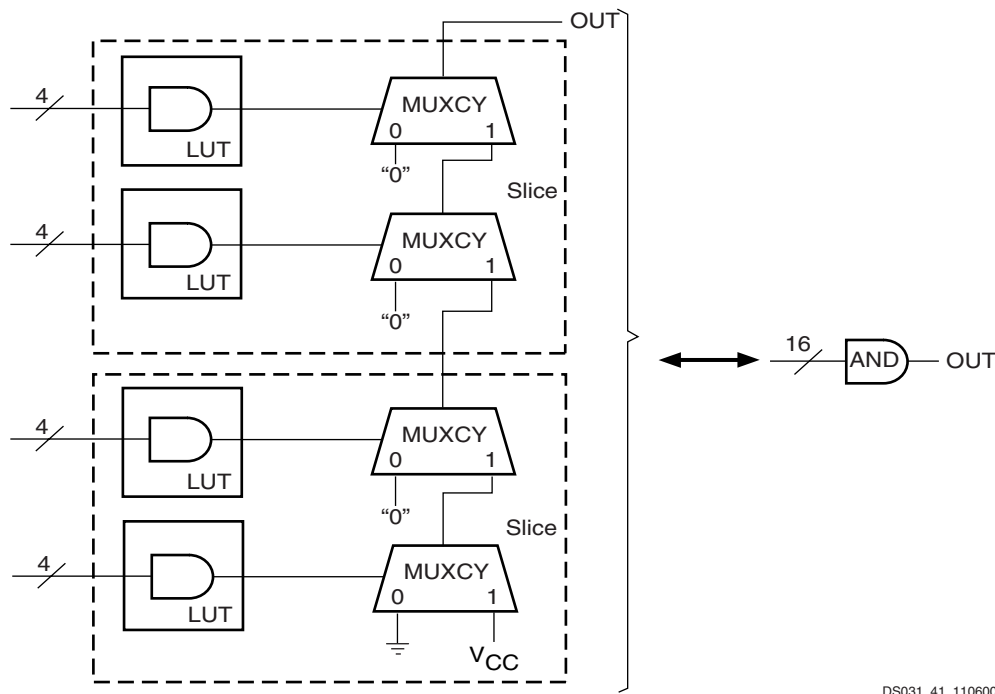


Figure 26: Wide-Input AND Gate (16 Inputs)

ments to begin changing state in response to the logic and the user clock.

The relative timing of these events can be changed via configuration options in software. In addition, the GTS and GWE events can be made dependent on the DONE pins of multiple devices all going High, forcing the devices to start synchronously. The sequence can also be paused at any stage, until lock has been achieved on any or all DCMs, as well as the DCI.

Readback

In this mode, configuration data from the Virtex-II FPGA device can be read back. Readback is supported only in the SelectMAP (master and slave) and Boundary-Scan mode.

Along with the configuration data, it is possible to read back the contents of all registers, distributed SelectRAM, and block RAM resources. This capability is used for real-time debugging. For more detailed configuration information, see the *Virtex-II Platform FPGA User Guide*.

Bitstream Encryption

Virtex-II devices have an on-chip decryptor using one or two sets of three keys for triple-key Data Encryption Standard (DES) operation. Xilinx software tools offer an optional encryption of the configuration data (bitstream) with a triple-key DES determined by the designer.

The keys are stored in the FPGA by JTAG instruction and retained by a battery connected to the V_{BATT} pin, when the device is not powered. Virtex-II devices can be configured with the corresponding encrypted bitstream, using any of the configuration modes described previously.

A detailed description of how to use bitstream encryption is provided in the *Virtex-II Platform FPGA User Guide*. For devices that support this feature, please contact your sales representative for specific ordering part number.

Partial Reconfiguration

Partial reconfiguration of Virtex-II devices can be accomplished in either Slave SelectMAP mode or Boundary-Scan mode. Instead of resetting the chip and doing a full configuration, new data is loaded into a specified area of the chip, while the rest of the chip remains in operation. Data is loaded on a column basis, with the smallest load unit being a configuration “frame” of the bitstream (device size dependent).

Partial reconfiguration is useful for applications that require different designs to be loaded into the same area of a chip, or that require the ability to change portions of a design without having to reset or reconfigure the entire chip.

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
11/07/00	1.0	Early access draft.
12/06/00	1.1	Initial release.
01/15/01	1.2	Added values to the tables in the Virtex-II Performance Characteristics and Virtex-II Switching Characteristics sections.
01/25/01	1.3	The data sheet was divided into four modules (per the current style standard). A note was added to Table 1 .
04/02/01	1.5	- Under Input/Output Individual Options, the range of values for optional pull-up and pull-down resistors was changed to 10 - 60 KΩ from 50 - 100 KΩ. - Skipped v1.4 to sync up modules. Reverted to traditional double-column format.
07/30/01	1.6	- Added Table 6. - Changed definition of multiply and divide integer ranges under Digital Clock Manager (DCM). - Made numerous minor edits throughout this module.
10/02/01	1.7	Updated descriptions under Digitally Controlled Impedance (DCI), Global Clock Multiplexer Buffers, Digital Clock Manager (DCM), and Creating a Design.
10/12/01	1.8	Made clarifying edits under Digital Clock Manager (DCM).
11/29/01	1.9	Changed bitstream lengths for each device in Table 26.

Table 25: Pipelined Multiplier Switching Characteristics

Description	Symbol	Speed Grade			Units
		-6	-5	-4	
Setup and Hold Times Before/After Clock					
Data Inputs	T _{MULIDCK} /T _{MULCKID}	3.00/ 0.00	3.45/ 0.00	3.89/ 0.00	ns, Max
Clock Enable	T _{MULIDCK_CE} /T _{MULCKID_CE}	0.72/ 0.00	0.80/ 0.00	0.86/ 0.00	ns, Max
Reset	T _{MULIDCK_RST} /T _{MULCKID_RST}	0.72/ 0.00	0.80/ 0.00	0.86/ 0.00	ns, Max
Clock to Output Pin					
Clock to Pin 35	T _{MULTCK_P35}	3.05	6.91	8.12	ns, Max
Clock to Pin 34	T _{MULTCK_P34}	2.95	6.75	7.93	ns, Max
Clock to Pin 33	T _{MULTCK_P33}	2.85	6.59	7.74	ns, Max
Clock to Pin 32	T _{MULTCK_P32}	2.76	6.43	7.56	ns, Max
Clock to Pin 31	T _{MULTCK_P31}	2.66	6.27	7.37	ns, Max
Clock to Pin 30	T _{MULTCK_P30}	2.56	6.11	7.19	ns, Max
Clock to Pin 29	T _{MULTCK_P29}	2.47	5.95	7.00	ns, Max
Clock to Pin 28	T _{MULTCK_P28}	2.37	5.79	6.81	ns, Max
Clock to Pin 27	T _{MULTCK_P27}	2.27	5.63	6.63	ns, Max
Clock to Pin 26	T _{MULTCK_P26}	2.17	5.47	6.44	ns, Max
Clock to Pin 25	T _{MULTCK_P25}	2.08	5.31	6.26	ns, Max
Clock to Pin 24	T _{MULTCK_P24}	1.98	5.15	6.07	ns, Max
Clock to Pin 23	T _{MULTCK_P23}	1.88	4.99	5.88	ns, Max
Clock to Pin 22	T _{MULTCK_P22}	1.79	4.83	5.70	ns, Max
Clock to Pin 21	T _{MULTCK_P21}	1.69	4.67	5.51	ns, Max
Clock to Pin 20	T _{MULTCK_P20}	1.59	4.51	5.33	ns, Max
Clock to Pin 19	T _{MULTCK_P19}	1.50	4.35	5.14	ns, Max
Clock to Pin 18	T _{MULTCK_P18}	1.40	4.19	4.95	ns, Max
Clock to Pin 17	T _{MULTCK_P17}	1.30	4.03	4.77	ns, Max
Clock to Pin 16	T _{MULTCK_P16}	1.20	3.87	4.58	ns, Max
Clock to Pin 15	T _{MULTCK_P15}	1.11	3.71	4.40	ns, Max
Clock to Pin 14	T _{MULTCK_P14}	1.01	3.55	4.21	ns, Max
Clock to Pin 13	T _{MULTCK_P13}	0.91	3.39	4.02	ns, Max
Clock to Pin 12	T _{MULTCK_P12}	0.91	3.23	3.84	ns, Max
Clock to Pin 11	T _{MULTCK_P11}	0.91	3.07	3.65	ns, Max
Clock to Pin 10	T _{MULTCK_P10}	0.91	2.91	3.47	ns, Max
Clock to Pin 9	T _{MULTCK_P9}	0.91	2.75	3.28	ns, Max
Clock to Pin 8	T _{MULTCK_P8}	0.91	2.59	3.09	ns, Max
Clock to Pin 7	T _{MULTCK_P7}	0.91	2.43	2.91	ns, Max
Clock to Pin 6	T _{MULTCK_P6}	0.91	2.27	2.72	ns, Max
Clock to Pin 5	T _{MULTCK_P5}	0.91	2.11	2.54	ns, Max
Clock to Pin 4	T _{MULTCK_P4}	0.91	1.95	2.35	ns, Max
Clock to Pin 3	T _{MULTCK_P3}	0.91	1.79	2.16	ns, Max
Clock to Pin 2	T _{MULTCK_P2}	0.91	1.63	1.98	ns, Max
Clock to Pin 1	T _{MULTCK_P1}	0.91	1.47	1.79	ns, Max
Clock to Pin 0	T _{MULTCK_P0}	0.91	1.31	1.61	ns, Max

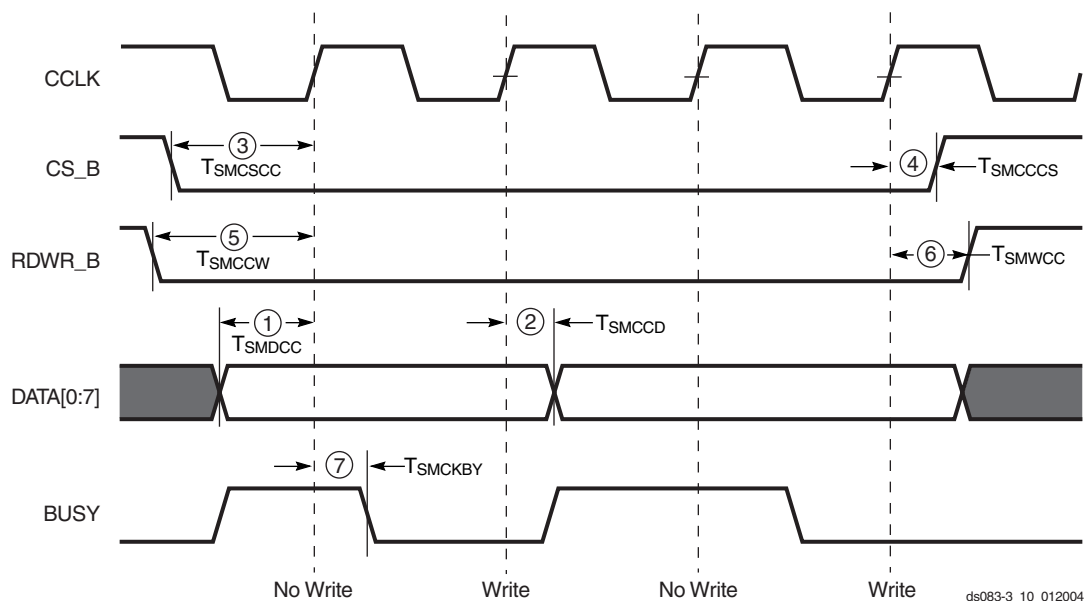


Figure 5: SelectMAP Mode Data Loading Sequence (Generic)

Table 32: SelectMAP Mode Write Timing Characteristics

	Description	Figure References	Symbol	Value	Units
CCLK	DATA[0:7] setup/hold	1/2	T_{SMDCD}/T_{SMCCD}	5.0/0.0	ns, min
	CS_B setup/hold	3/4	T_{SMCSCC}/T_{SMCCCS}	7.0/0.0	ns, min
	RDWR_B setup/hold	5/6	T_{SMCCW}/T_{SMWCC}	7.0/0.0	ns, min
	BUSY propagation delay	7	T_{SMCKBY}	12.0	ns, max
	Maximum start-up frequency		$F_{CC_STARTUP}$	50	MHz, max
	Maximum frequency		$F_{CC_SELECTMAP}$	50	MHz, max
	Maximum frequency with no handshake		F_{CCNH}	50	MHz, max

Source-Synchronous Switching Characteristics

The parameters in this section provide the necessary values for calculating timing budgets for Virtex-II source-synchronous transmitter and receiver data-valid windows.

Table 45: Duty Cycle Distortion and Clock-Tree Skew

Description	Symbol	Device	Speed Grade			Units
			-6	-5	-4	
Duty Cycle Distortion ⁽¹⁾	T_{DCD_CLK0}	All	140	140	140	ps
	T_{DCD_CLK180}	All	50	50	50	ps
Clock Tree Skew ⁽²⁾	T_{CKSKEW}	XC2V40	50	50	60	ps
		XC2V80	50	50	60	ps
		XC2V250	50	50	60	ps
		XC2V500	50	50	60	ps
		XC2V1000	80	80	90	ps
		XC2V1500	80	80	90	ps
		XC2V2000	100	100	110	ps
		XC2V3000	100	100	110	ps
		XC2V4000	400	400	450	ps
		XC2V6000	500	500	550	ps
		XC2V8000		600	650	ps

Notes:

- These parameters represent the worst-case duty cycle distortion observable at the pins of the device using LVDS output buffers. For cases where other I/O standards are used, IBIS can be used to calculate any additional duty cycle distortion that might be caused by asymmetrical rise/fall times.
 T_{DCD_CLK0} applies to cases where local (IOB) inversion is used to provide the negative-edge clock to the DDR element in the I/O.
 T_{DCD_CLK180} applies to cases where the CLK180 output of the DCM is used to provide the negative-edge clock to the DDR element in the I/O.
- This value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to your application.

Table 46: Package Skew

Description	Symbol	Device/Package	Value	Units
Package Skew ⁽¹⁾	$T_{PKGSKEW}$	XC2V1000 / FF896	130	ps
		XC2V3000 / FF1152	115	ps
		XC2V3000 / BF957	130	ps
		XC2V4000 / FF1152	130	ps
		XC2V4000 / FF1517	200	ps
		XC2V4000 / BF957	140	ps
		XC2V6000 / FF1152	90	ps
		XC2V6000 / FF1517	105	ps
		XC2V6000 / BF957	105	ps

Notes:

- These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball (7.1ps per mm).
- Package trace length information is available for these device/package combinations. This information can be used to deskew the package.

Table 8: FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
0	IO_L67P_0	C10		
0	IO_L69N_0	F10		
0	IO_L69P_0/VREF_0	G10		
0	IO_L70N_0	E10		
0	IO_L70P_0	D10		
0	IO_L72N_0	A10		
0	IO_L72P_0	A11		
0	IO_L73N_0	F11	NC	
0	IO_L73P_0	E11	NC	
0	IO_L75N_0	G11	NC	
0	IO_L75P_0/VREF_0	H11	NC	
0	IO_L76N_0	D11	NC	
0	IO_L76P_0	C11	NC	
0	IO_L78N_0	B11	NC	
0	IO_L78P_0	B12	NC	
0	IO_L91N_0/VREF_0	G12		
0	IO_L91P_0	H12		
0	IO_L92N_0	F12		
0	IO_L92P_0	E12		
0	IO_L93N_0	D12		
0	IO_L93P_0	C12		
0	IO_L94N_0/VREF_0	G13		
0	IO_L94P_0	H13		
0	IO_L95N_0/GCLK7P	F13		
0	IO_L95P_0/GCLK6S	E13		
0	IO_L96N_0/GCLK5P	D13		
0	IO_L96P_0/GCLK4S	C13		
1	IO_L96N_1/GCLK3P	H14		
1	IO_L96P_1/GCLK2S	H15		
1	IO_L95N_1/GCLK1P	G14		
1	IO_L95P_1/GCLK0S	F14		
1	IO_L94N_1	E14		
1	IO_L94P_1/VREF_1	D14		
1	IO_L93N_1	A12		
1	IO_L93P_1	A13		
1	IO_L92N_1	A14		

Table 11: FF896 BGA — XC2V1000, XC2V1500, and XC2V2000

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
4	IO_L73P_4	AJ12	NC	NC
4	IO_L74N_4	AE13	NC	NC
4	IO_L74P_4	AE14	NC	NC
4	IO_L75N_4	AF13	NC	NC
4	IO_L75P_4/VREF_4	AG13	NC	NC
4	IO_L76N_4	AK13	NC	NC
4	IO_L76P_4	AK12	NC	NC
4	IO_L77N_4	AB14	NC	NC
4	IO_L77P_4	AB15	NC	NC
4	IO_L78N_4	AF15	NC	NC
4	IO_L78P_4	AF14	NC	NC
4	IO_L91N_4/VREF_4	AJ14		
4	IO_L91P_4	AJ15		
4	IO_L92N_4	AC14		
4	IO_L92P_4	AC15		
4	IO_L93N_4	AG15		
4	IO_L93P_4	AG14		
4	IO_L94N_4/VREF_4	AK14		
4	IO_L94P_4	AK15		
4	IO_L95N_4/GCLK3S	AD15		
4	IO_L95P_4/GCLK2P	AE15		
4	IO_L96N_4/GCLK1S	AH14		
4	IO_L96P_4/GCLK0P	AH15		
5	IO_L96N_5/GCLK7S	AH16		
5	IO_L96P_5/GCLK6P	AH17		
5	IO_L95N_5/GCLK5S	AE16		
5	IO_L95P_5/GCLK4P	AD16		
5	IO_L94N_5	AJ16		
5	IO_L94P_5/VREF_5	AJ17		
5	IO_L93N_5	AG17		
5	IO_L93P_5	AG16		
5	IO_L92N_5	AC16		
5	IO_L92P_5	AC17		
5	IO_L91N_5	AK17		
5	IO_L91P_5/VREF_5	AK18		
5	IO_L78N_5	AF17	NC	NC

Table 11: FF896 BGA — XC2V1000, XC2V1500, and XC2V2000

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
6	IO_L20P_6	AE26		
6	IO_L20N_6	AD26		
6	IO_L21P_6	AG30		
6	IO_L21N_6/VREF_6	AF30		
6	IO_L22P_6	AD25		
6	IO_L22N_6	AC25		
6	IO_L23P_6	AE28		
6	IO_L23N_6	AD28		
6	IO_L24P_6	AD29		
6	IO_L24N_6	AE29		
6	IO_L43P_6	AC24		
6	IO_L43N_6	AB24		
6	IO_L44P_6	AD27		
6	IO_L44N_6	AC27		
6	IO_L45P_6	AC26		
6	IO_L45N_6/VREF_6	AB26		
6	IO_L46P_6	AA23		
6	IO_L46N_6	Y23		
6	IO_L47P_6	AC28		
6	IO_L47N_6	AB28		
6	IO_L48P_6	AD30		
6	IO_L48N_6	AE30		
6	IO_L49P_6	AB25		
6	IO_L49N_6	AA25		
6	IO_L50P_6	AA24		
6	IO_L50N_6	Y24		
6	IO_L51P_6	AC29		
6	IO_L51N_6/VREF_6	AB30		
6	IO_L52P_6	Y25		
6	IO_L52N_6	W25		
6	IO_L53P_6	AB27		
6	IO_L53N_6	AA27		
6	IO_L54P_6	AA29		
6	IO_L54N_6	AB29		
6	IO_L67P_6	W23	NC	
6	IO_L67N_6	V23	NC	
6	IO_L68P_6	AA26	NC	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
3	IO_L83P_3	Y4	NC
3	IO_L82N_3	W11	NC
3	IO_L82P_3	V11	NC
3	IO_L81N_3/VREF_3	W8	NC
3	IO_L81P_3	Y8	NC
3	IO_L80N_3	W2	NC
3	IO_L80P_3	Y1	NC
3	IO_L79N_3	AA3	NC
3	IO_L79P_3	AB3	NC
3	IO_L78N_3	Y6	
3	IO_L78P_3	AA6	
3	IO_L77N_3	AA4	
3	IO_L77P_3	AB4	
3	IO_L76N_3	Y7	
3	IO_L76P_3	AA8	
3	IO_L75N_3/VREF_3	Y10	
3	IO_L75P_3	AA10	
3	IO_L74N_3	AA1	
3	IO_L74P_3	AB1	
3	IO_L73N_3	AA5	
3	IO_L73P_3	AB5	
3	IO_L72N_3	AA9	
3	IO_L72P_3	Y9	
3	IO_L71N_3	AA2	
3	IO_L71P_3	AB2	
3	IO_L70N_3	AB6	
3	IO_L70P_3	AC6	
3	IO_L69N_3/VREF_3	AD1	
3	IO_L69P_3	AC1	
3	IO_L68N_3	AC3	
3	IO_L68P_3	AD3	
3	IO_L67N_3	AC4	
3	IO_L67P_3	AD4	
3	IO_L54N_3	AB7	
3	IO_L54P_3	AC7	
3	IO_L53N_3	AC2	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
7	IO_L75N_7	R28	
7	IO_L74P_7	R26	
7	IO_L74N_7	P26	
7	IO_L73P_7	N31	
7	IO_L73N_7	P31	
7	IO_L72P_7	N30	
7	IO_L72N_7	P30	
7	IO_L71P_7	R25	
7	IO_L71N_7	P25	
7	IO_L70P_7	L34	
7	IO_L70N_7	M34	
7	IO_L69P_7/VREF_7	P29	
7	IO_L69N_7	N29	
7	IO_L68P_7	P27	
7	IO_L68N_7	N27	
7	IO_L67P_7	L32	
7	IO_L67N_7	M32	
7	IO_L54P_7	L31	
7	IO_L54N_7	M31	
7	IO_L53P_7	K29	
7	IO_L53N_7	L30	
7	IO_L52P_7	L33	
7	IO_L52N_7	M33	
7	IO_L51P_7/VREF_7	M29	
7	IO_L51N_7	L29	
7	IO_L50P_7	M28	
7	IO_L50N_7	N28	
7	IO_L49P_7	K30	
7	IO_L49N_7	K31	
7	IO_L48P_7	H32	
7	IO_L48N_7	J32	
7	IO_L47P_7	N26	
7	IO_L47N_7	M26	
7	IO_L46P_7	J33	
7	IO_L46N_7	K33	
7	IO_L45P_7/VREF_7	H33	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
2	VCCO_2	R11	
2	VCCO_2	R5	
2	VCCO_2	P12	
2	VCCO_2	P11	
2	VCCO_2	N12	
2	VCCO_2	N11	
2	VCCO_2	M11	
2	VCCO_2	K1	
2	VCCO_2	G4	
3	VCCO_3	AH4	
3	VCCO_3	AE1	
3	VCCO_3	AC11	
3	VCCO_3	AB12	
3	VCCO_3	AB11	
3	VCCO_3	AA12	
3	VCCO_3	AA11	
3	VCCO_3	Y12	
3	VCCO_3	Y11	
3	VCCO_3	Y5	
3	VCCO_3	W12	
3	VCCO_3	W1	
3	VCCO_3	V12	
4	VCCO_4	AP16	
4	VCCO_4	AP10	
4	VCCO_4	AL7	
4	VCCO_4	AK15	
4	VCCO_4	AD15	
4	VCCO_4	AD14	
4	VCCO_4	AD13	
4	VCCO_4	AD12	
4	VCCO_4	AC17	
4	VCCO_4	AC16	
4	VCCO_4	AC15	
4	VCCO_4	AC14	
4	VCCO_4	AC13	
5	VCCO_5	AP25	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
NA	GND	V19	
NA	GND	V18	
NA	GND	V17	
NA	GND	V16	
NA	GND	V15	
NA	GND	V14	
NA	GND	U21	
NA	GND	U20	
NA	GND	U19	
NA	GND	U18	
NA	GND	U17	
NA	GND	U16	
NA	GND	U15	
NA	GND	U14	
NA	GND	T26	
NA	GND	T21	
NA	GND	T20	
NA	GND	T19	
NA	GND	T18	
NA	GND	T17	
NA	GND	T16	
NA	GND	T15	
NA	GND	T14	
NA	GND	T9	
NA	GND	R33	
NA	GND	R21	
NA	GND	R20	
NA	GND	R19	
NA	GND	R18	
NA	GND	R17	
NA	GND	R16	
NA	GND	R15	
NA	GND	R14	
NA	GND	R2	
NA	GND	P28	
NA	GND	P21	

